

### Features

- This series is designed for average power 300W approximated ESD protection, different  $V_{RWM}$ , different peak pulse power available.
- Protects one I/O or power line.
- Low clamping voltage.
- Working voltages: 3.3V, 5.0V, 12V, 15V
- Low leakage current.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free.
- Suffix "-Q1" for AEC-Q101

### IEC compatibility

- IEC61000-4-2 (ESD)  $\pm 30$ kV (air),  $\pm 25$ kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)

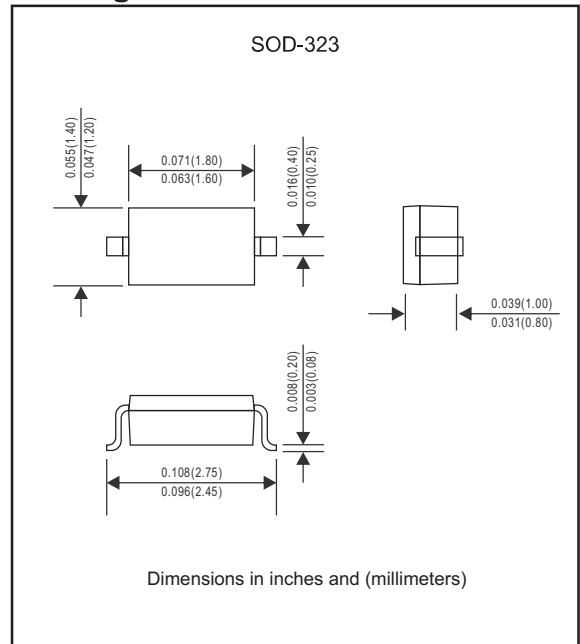
### Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- Pagers

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

### Package outline



### Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

| PARAMETER                            | CONDITIONS         | SYMBOL    | VALUE       | UNIT             |
|--------------------------------------|--------------------|-----------|-------------|------------------|
| Lead solder temperature-maximum      | 10 second duration | $T_L$     | 260         | $^\circ\text{C}$ |
| Operating junction temperature range |                    | $T_J$     | -55 to +125 | $^\circ\text{C}$ |
| Storage temperature range            |                    | $T_{STG}$ | -55 to +150 | $^\circ\text{C}$ |

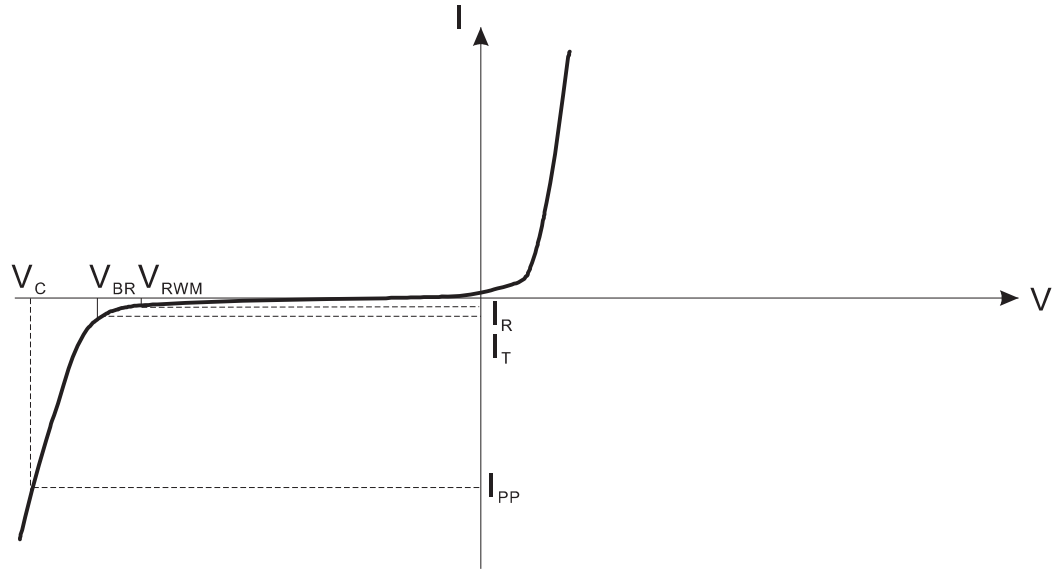
### Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

| Part No.    | $V_{RWM}$<br>(V)<br>(Max.) | $I_R$ ( $\mu\text{A}$ )<br>@ $V_{RWM}$<br>(Max.) | $V_{BR}$ (V)<br>@ $I_T$<br>(Note 2)<br>(Min.) | $I_T$<br>(mA) | $V_C$ (V)<br>@ $I_{PP}=1.0\text{A}$<br>(Max.) | $I_{PP}$<br>(A)<br>(Max.) | $V_C$ (V)(Note 1)<br>@ $\text{Max } I_{PP}$<br>(Max.) | $P_{PK}$<br>(W)<br>(Note 1)<br>(Max.) | $C_J$<br>(pF)<br>(Typ.) |
|-------------|----------------------------|--|---|---------------|---|---------------------------|---|---------------------------------------|-------------------------|
| ESD3Z3.3-Q1 | 3.3                        | 40   | 4.0   | 1.0           | 6.5   | 20.0                      | 15.0  | 300                                   | 450                     |
| ESD3Z5.0-Q1 | 5.0                        | 10   | 6.0   | 1.0           | 9.8   | 17.0                      | 18.0  | 306                                   | 300                     |
| ESD3Z12-Q1  | 12                         | 1  | 13.3  | 1.0           | 19.0  | 11.0                      | 32.0  | 352                                   | 130                     |
| ESD3Z15-Q1  | 15                         | 1  | 16  | 1.0           | 24.0  | 10.0                      | 38.0  | 380                                   | 120                     |

Notes 1: Surge current waveform per Fig.1

2:  $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of  $25^\circ\text{C}$ .

**Typical characteristics** (at  $T_A=25^\circ\text{C}$  unless otherwise noted)



Uni-Directional TVS

- $V_C$  : Clamping voltage @  $I_{PP}$
- $I_{PP}$  : Maximum reverse peak pulse current
- $V_{RWM}$  : Maximum working peak reverse voltage
- $I_R$  : Maximum reverse leakage current @  $V_{RWM}$
- $V_{BR}$  : Breakdown voltage @  $I_T$
- $I_T$  : Test current
- $C_J$  : Max. capacitance @  $V_R = 0\text{V}$  and  $f = 1\text{MHz}$

### Rating and characteristic curves

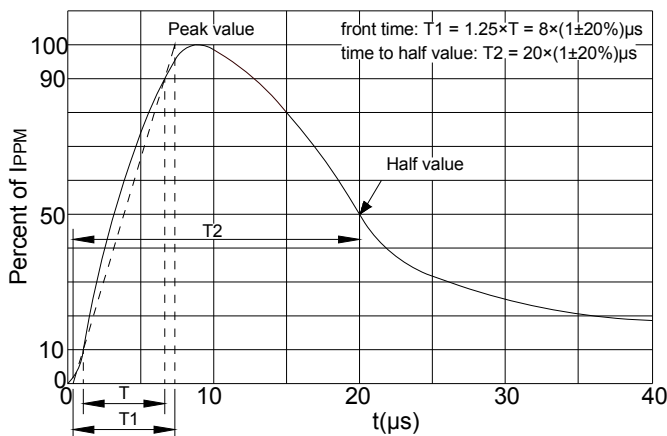


FIG.1: Pulse Waveform curve

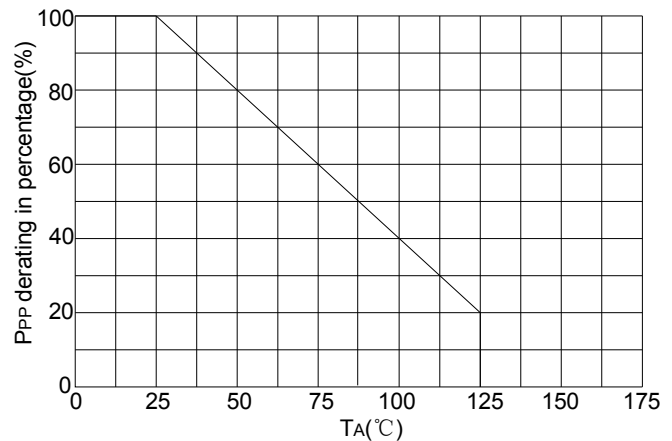




FIG.2: Pulse derating curve

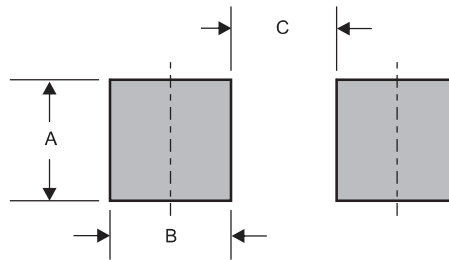
## Pinning information

| Pin   | Simplified outline  | Symbol  |
|---|---|---|
| Uni-Directional<br>Pin1 cathode<br>Pin2 anode |  |  |

## Marking

| Type number | Marking code |
|-------------|--------------|
| ESD3Z3.3-Q1 | 03W/03       |
| ESD3Z5.0-Q1 | 05W/D05      |
| ESD3Z12-Q1  | 12W/D12      |
| ESD3Z15-Q1  | 15W/D15      |

## Suggested solder pad layout



Dimensions in inches and (millimeters)

| PACKAGE | A            | B            | C            |
|---------|--------------|--------------|--------------|
| SOD-323 | 0.033 (0.83) | 0.025 (0.63) | 0.063 (1.60) |